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**Micro-electromechanical systems (MEMS)
technology-Technical specification of automotive grade
pressure sensor based on MEMS technology**

微机电系统（MEMS）技术 基于MEMS技术的车规级压力传感器技术规范

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Foreword

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Micro-electromechanical systems (MEMS) technology is based on MEMS Technical specifications for automotive-grade pressure sensors

1 Scope

This document specifies the classification, basic requirements, technical requirements and test methods for automotive-grade pressure sensors based on MEMS technology.

This document is applicable to automotive-grade pressure sensors based on MEMS technology, and other pressure sensors may refer to it.

2 Normative references

GB/T 2423.22

GB/T 2423.33

GB/T 2423.51

GB/T 4937.4

GB/T 4937.12

GB/T 4937.13

GB/T 7665

GB/T 18655

GB/T 19951

GB/T 21437.3

GB/T 26111

GB/T 28046.5

GB/T 33014.2

GB/T 33014.4

GB/T 33014.9

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